

ABSTRACT OF THE DISCLOSURE

PROCESS SOLUTIONS CONTAINING SURFACTANTS

Process solutions comprising one or more surfactants are used to reduce the

5 number of defects in the manufacture of semiconductor devices. In certain embodiments, the process solution may reduce post-development defects such as pattern collapse or line width roughness when employed as a rinse solution either during or after the development of the patterned photoresist layer. Also disclosed is a method for reducing the number of defects such as pattern collapse and/or line width roughness

10 on a plurality of photoresist coated substrates employing the process solution of the present invention.

Figure 1b